PATENT NUMBER and

## **U.S. UTILITY Patent Application**

	APPL NUM	FILING DATE	,	SUBCLASS	GAU	EXAMINER	7					
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	**APPLICANTS: Yeo Yong; Khan Navas; Iyer Mahadevan;											
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TITLE : Enhanced chip scale package for wire bond dies												
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		F-177		Total Claims	Print Claim for
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